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United States Patent [19]

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Akimoto

[45] Date of Patent: **** Nov. 16, 1993**

[54] **SUPPLY NOZZLE FOR APPLYING LIQUID RESIST TO A SEMICONDUCTOR WAFER**

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Kumamoto, both of Japan

[**] Term: **14 Years**

[57] CLAIM

[21] Appl. No.: **748,061**

The ornamental design for supply nozzle for applying liquid resist to a semiconductor wafer, as shown and described.

[22] Filed: **Aug. 21, 1991**

DESCRIPTION

[30] **Foreign Application Priority Data**

Feb. 22, 1991 [JP] Japan 3-4465

[52] U.S. Cl. **D23/213**

[58] Field of Search D23/200, 213-229;
118/52, 302, 313, 321; 414/DIG. 1-DIG. 7,
225; D13/102, 182

FIG. 1 is a top, front and left side perspective view of supply nozzle for applying liquid resist to a semiconductor wafer showing my new design;

FIG. 2 is a top plan view thereof;

FIG. 3 is a front elevational view thereof, the rear being a mirror image;

FIG. 4 is a left side elevational view thereof;

FIG. 5 is a right side elevational view thereof;

FIG. 6 is a bottom plan view thereof;

FIG. 7 is a cross-sectional view thereof taken on line 7-7 in FIG. 3; and,

FIG. 8 is a cross-sectional view thereof taken on line 8-8 in FIG. 2.

[56] **References Cited**

U.S. PATENT DOCUMENTS

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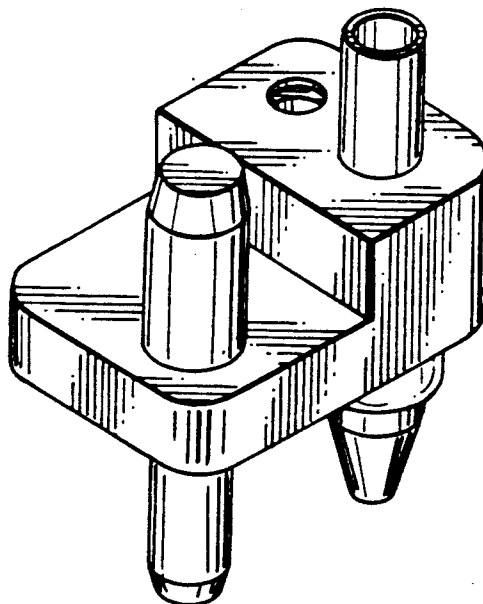


FIG. 1

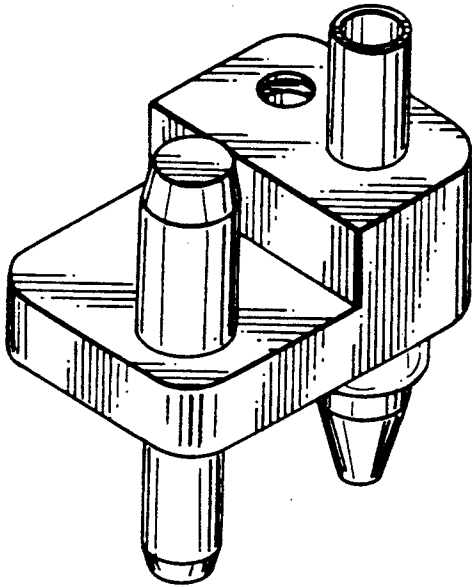


FIG. 2

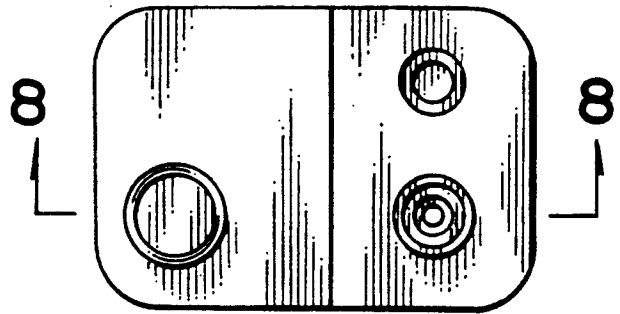


FIG. 4

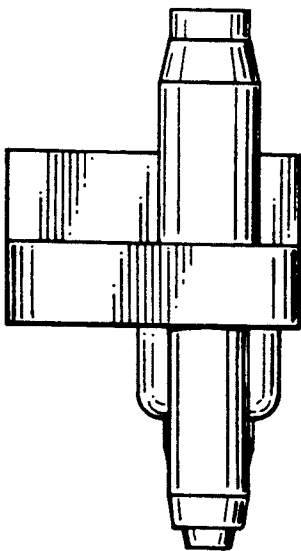


FIG. 3

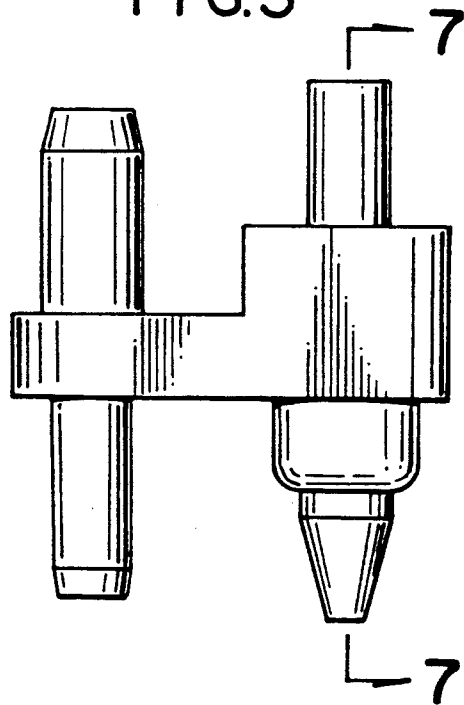


FIG. 5

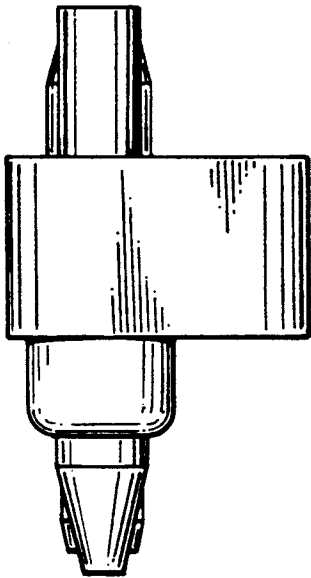


FIG. 6

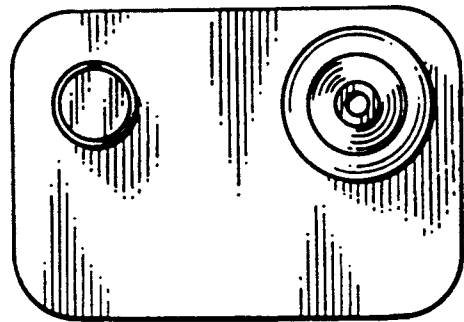


FIG. 7

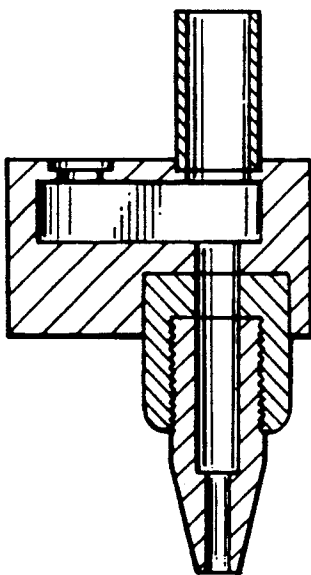


FIG. 8

